

REMARKS

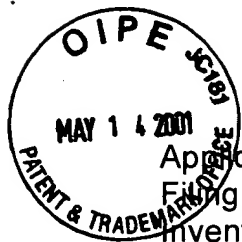
Claims 42-44 are cancelled. Claim 53 is amended. Claims 60-36 are added. Claims 53-55 and 60-60 are in the application for consideration.

Examination on the merits in light of the above is requested.

Respectfully submitted,

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By: 
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/783,835
Filing Date February 14, 2001
Inventor Shozo Nagano et al.
Assignee Honeywell International, Inc.
Group Art Unit Unknown
Examiner Unknown
Attorney's Docket No. 30-5000-(4015)-Div3
Title: Physical Vapor Deposition Target

**VERSION WITH MARKINGS TO SHOW CHANGES MADE
ACCOMPANYING SUPPLEMENTAL PRELIMINARY AMENDMENT**

In the Claims

The claims have been amended as follows. Underlines indicate
insertions and ~~strikeouts~~ indicate deletions.

Cancel claims 42-44.

53. (Amended) A physical vapor deposition target comprising an alloy
of copper and one or more other elements, the one or more other elements
being present in the alloy at a total concentration from less than 1.0 at%
to 0.001 at% and being selected from the group consisting of ~~V, Nb, Ta, Cr,~~
~~Mo, W, Mn, Tc, Re, Fe, Ru, Os, Co, Rh, Ni, Pd, Pt, Au,~~ and ~~Tl, and Pb.~~

60. (New) The physical vapor deposition target of claim 53 wherein the element comprises Mo.

61. (New) The physical vapor deposition target of claim 53 wherein the element comprises Tc.

62. (New) The physical vapor deposition target of claim 53 wherein the element comprises Re.

63. (New) The physical vapor deposition target of claim 53 wherein the element comprises Tl.

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